

COMPLETE LISTING OF THE CLAIMS

The following lists all of the claims that are or were in the above-identified patent application. The status identifiers respectively provided in parentheses following the claim numbers indicate the current statuses of the claims.

1. (Currently Amended) A device comprising:
a sub-mount containing conductive traces;
a die mounted on the sub-mount and containing an edge-emitting laser that is
electrically coupled to the conductive traces; and
a reflector positioned to reflect an optical signal from the edge-emitting laser through the sub-mount.
2. (Original) The device of claim 1, further comprising an alignment post attached to the sub-mount where the optical signal emerges from the sub-mount.
3. (Original) The device of claim 1, further comprising a lens in the path of the optical signal.
4. (Original) The device of claim 3, wherein the lens is integrated in the sub-mount along the path of the optical signal.
5. (Original) The device of claim 3, wherein the lens comprises a diffractive optical element.
6. (Original) The device of claim 1, wherein the reflector comprises a portion of an inner wall of a cavity in a cap overlying the die.
7. (Original) The device of claim 6, wherein the cap attaches to the sub-mount to hermetically seal the die in the cavity.
8. (Original) The device of claim 1, further comprising a transparent encapsulant attached to the sub-mount and encasing the die.
9. (Original) The device of claim 8, wherein the encapsulant comprises silicone.

10. (Currently Amended) A process comprising:
mounting a die containing a laser on a surface of a sub-mount;
electrically connecting [[a]] the laser to [[a]] electrical traces in the sub-mount; and
attaching a reflector to the sub-mount in a position such that an optical signal from
the laser is reflected through the sub-mount.

11. (Original) The process of claim 10, further comprising attaching an alignment
post to the sub-mount where the optical signal emerges.

12. (Original) The process of claim 10, further comprising encapsulating the laser
in a transparent material that protects the laser.

13. (Original) The process of claim 12, wherein the transparent material
comprises silicone.

14. (Original) The process of claim 10, wherein the laser is an edge-emitting
laser.

15. (Original) The process of claim 10, wherein electrically connecting the laser
comprises connecting a plurality of lasers to a sub-mount wafer that includes the sub-
mount.

16. (Original) The process of claim 15, further comprising cutting the sub-mount
wafer to separate the sub-mount from similar sub-mounts.

17. (New) The process of claim 10, wherein the reflector reflects the optical
signal through the surface on which the die is mounted.

18. (New) The device of claim 1, wherein the die is mounted on a first surface of
the sub-mount, and the reflector directs the optical signal through the first surface.

19. (New) The device of claim 18, further comprising an alignment post attached
to a second surface of the sub-mount where the optical signal emerges from the sub-
mount.